



materials



an Open Access Journal by MDPI

Select Papers from the 21st European Microelectronics and Packaging Conference and Exhibition—EMPC 2017

Guest Editors:

Dr. Piotr Jasinski

Gdańsk University of Technology

Prof. Dr. Andrzej Dziedzic

Faculty of Electronics, Photonics
and Microsystems, Wrocław
University of Science and
Technology, Wybrzeże
Wyspiańskiego 27, 50-370
Wrocław, Poland

Deadline for manuscript
submissions:

closed (31 January 2018)

Message from the Guest Editors

Dear Colleagues,

The 21st European Microelectronics and Packaging Conference and Exhibition (EMPC 2017) will be held in Warsaw, Poland, 10–13 September, 2017, and will be devoted to recent developments in the field of microelectronics and packaging technologies. The materials related aspects in these fields are very crucial to extend the current limits.

This Special Issue selects excellent papers from EMPC 2017 that are related to materials development. The issue will cover the materials oriented scopes of advanced packaging and interconnects, electronic components assembly, printed, hybrid and flexible electronics, thermal management and functional systems. We invite investigators to contribute original research articles, as well as review articles, to this Special Issue.

Dr. Piotr Jasinski

Prof. Andrzej Dziedzic

Guest Editors



mdpi.com/si/10938

Special Issue



an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Maryam Tabrizian

1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada

2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, CaPlus / SciFinder, Inspec, Astrophysics Data System, and other databases.

Journal Rank: JCR - Q2 (*Metallurgy & Metallurgical Engineering*) / CiteScore - Q2 (*Condensed Matter Physics*)

Contact Us

Materials Editorial Office
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/materials
materials@mdpi.com
[X@Materials_Mdpi](https://twitter.com/Materials_Mdpi)